EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	44068	(semiconductor or die or dice or chip or IC) and (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4 or groov$3 or recess or open$3) with (edge or periphery or end)	USPAT	OR	ON	2007/04/04 15:57
S2	48220	(semiconductor or die or dice or chip or IC) and (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4 or groov$3 or recess or open$3) with (edge or peripher$3 or end$3 or perimeter)	USPAT	OR	ON	2007/04/04 15:58
S3	30560	(semiconductor or die or dice or chip or IC) and (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4 or groov$3 or recess or stair) with (edge or peripher$3 or end$3 or perimeter)	USPAT	OR	ON	2007/04/04 15:58
S4	9255	(semiconductor or die or dice or chip or IC) same (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4 or groov$3 or recess or stair) with (edge or peripher$3 or end$3 or perimeter)	USPAT	OR	ON	2007/04/04 15:59
S5	7879	(semiconductor or die or dice or chip or IC) same (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4 or groov$3 or stair) with (edge or peripher$3 or end$3 or perimeter)	USPAT	OR	ON	2007/04/04 15:59
S6	4709	(semiconductor or die or dice or chip or IC) same (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4 or groov$3 or stair) with (edge or peripher$3 or perimeter)	USPAT	OR	ON	2007/04/04 16:00
S7	3660	(semiconductor or die or dice or chip or IC) same (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4 or stair) with (edge or peripher$3 or perimeter)	USPAT	OR	ON	2007/04/04 16:00

EAST Search History

S8	3658	(semiconductor or die or dice or chip or IC) same (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3) with (step$4) with (edge or peripher$3 or perimeter)	USPAT	OR	ON	2007/04/04 16:00
S9	3660	(semiconductor or die or dice or chip or IC) same (step$4 or stair) with (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 16:00
S10	127	(semiconductor or die or dice or chip or IC) same (step$4 or stair) near (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 16:01
S11	286	(semiconductor or die or dice or chip or IC) same (step$4 or stair or groov$3) near (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 16:29
S12	42	("3328650" | "3589000" | "3591839" | "3730969" | "4001859" | "4081901" | "4143385" | "4179802" | "4193082" | "4231154" | "4338577" | "4396457" | "4577398" | "4791075" | "4803546" | "4953005").PN. OR ("5126818"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 16:14
S13	38	("2609429" | "3351698" | "3355635" | "3366793" | "3370174" | "3456335" | "3871015" | "3886581" | "4005457" | "4012833" | "4058821").PN. OR ("4143385"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 16:24
S14	49	("4143385" | "4483067" | "4494688" | "4928387" | "4940181" | "4955132").PN. OR ("5081520"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 16:26

EAST Search History

S15	1119	(semiconductor or die or dice or chip or IC) and (step$4 or stair or groov$3) near (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 17:49
S16	833	S15 not S11	USPAT	OR	ON	2007/04/04 16:30
S17	3482	S9 not S15	USPAT	OR	ON	2007/04/04 17:48
S18	13813	(semiconductor or die or dice or chip or IC) and (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 17:50
S19	2134	(semiconductor or die or dice or chip or IC) and (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) near (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 19:19
S20	1875	S19 not S15	USPAT	OR	ON	2007/04/04 17:50

| S21 | 179 | ("20010048157" \| "20010053563" \| "20020027080" \| "20020045611" \| "20020079594" \| "20020127769" \| "20020142513" \| "20030012930" \| "20030042595" \| "20040026773" \| "20040212055" \| "20040217454" \| "3239496" \| "4074342" \| "4415403" \| "4807021" \| "4818728" \| "4954875" \| "5148265" \| "5346861" \| "5347159" \| "5366794" \| "5385869" \| "5386341" \| "5397921" \| "5404044" \| "5409865" \| "5422205" \| "5438477" \| "5448511" \| "5468681" \| "5468995" \| "5489804" \| "5504277" \| "5598033" \| "5608265" \| "5646446" \| "5663530" \| "5668405" \| "5674785" \| "5679977" \| "5683942" \| "5697148" \| "5702662" \| "5710071" \| "5719449" \| "5721151" \| "5723347" \| "5739585" \| "5742100" \| "5747982" \| "5752182" \| "5758413" \| "5768109" \| "5777391" \| "5798285" \| "5798567" \| "5805422" \| "5812378" \| "5818113" \| "5821624" \| "5834338" \| "5834366" \| "5834848" \| "5835355" \| "5843808" \| "5844168" \| "5844315" \| "5858413" \| "5866953" \| "5886408" \| "5891753" \| "5892271" \| "5898224" \| "5905303" \| "5973389" \| "5973404" \| "5977640" \| "5982030" \| "5984691" \| "5986460" \| "5990545" \| "5991161" \| "6005776" \| "6008543" \| "6011694" \| "6013948" \| "6020629" \| "6022761" \| "6024584" \| "6027346" \| "6028365" \| "6034427" \| "6037665" \| "6039889" \| "6040630" \| "6048755" \| "6050832" \| "6057178" \| "6060782" \| "6064114" \| "6072233" \| "6074897" \| "6075710" \| "6079991" \| "6093035" \| "6116921" \| "6124631" \| "6127736" \| "6133072" \| "6133637" \| "6137062" \| "6137164" \| "6137183" \| "6157541" \| "6165885" \| "6172422" \| "6177723" \| "6179598" \| "6180881" \| "6191487").PN. OR ("6208521" \| "6208525" \| "6212768" \| "6214156" \| "6217343" \| "6218202" \| "6219911" \| "6221763" \| "6222265" \| "6225688" \| "6229711" \| "6232666" \| "6239496" \| "6242932" \| "6262895" \| "6265775" \| "6271469" \| "6281046" \| "6285081" \| "6291265" \| "6291775" \| "6291884" \| "6294455" \| "6295730" | US-PGPUB; USPAT; USOCR | OR | OFF | 2007/04/04 19:00 |

EAST Search History

S22	4	("4219835" | "5314844").PN. OR ("6573157").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 19:00
S23	55	(semiconductor or die or dice or chip or IC) and (ledge) with (edge or peripher$3 or perimeter) near (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 19:14
S24	4	("5430734" | "5838159" | "6426638" | "6747352").PN. OR ("7148505"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 19:17
S25	4709	(semiconductor or die or dice or chip or IC) same (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 19:22
S26	4108	S25 not S19	USPAT	OR	ON	2007/04/04 19:19
S27	13813	(semiconductor or die or dice or chip or IC) and (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3 or mount$3)	USPAT	OR	ON	2007/04/04 19:19
S28	4273	(semiconductor or die or dice or chip or IC) same (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or carrier or module or mount$3)	USPAT	OR	ON	2007/04/04 19:21
S29	3947	(semiconductor or die or dice or chip or IC) same (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or mount$3)	USPAT	OR	ON	2007/04/04 19:22
S30	3975	(semiconductor or die or dice or chip or IC) same (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or carrier or module or board or PCB or interposer or interconnect$3)	USPAT	OR	ON	2007/04/04 19:22
S31	3421	S30 not S19	USPAT	OR	ON	2007/04/04 19:22
S32	3717	(semiconductor or die or dice or chip or IC) same (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or carrier or module or board)	USPAT	OR	ON	2007/04/04 19:23

EAST Search History

S33	3345	(semiconductor or die or dice or chip or IC) same (step$4 or stair or groov$3) with (edge or peripher$3 or perimeter) with (substrate or carrier)	USPAT	OR	ON	2007/04/04 19:23
S34	2883	S33 not S19	USPAT	OR	ON	2007/04/04 19:23
S35	10	("3838501" | "4937129" | "5152857" | "5481386" | "5892271" | "5892273" | "5925931" | "5936304" | "6018249" | "6049124").PN. OR ("6657282").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 20:42
S36	29	("5202754" | "5646067" | "5879964" | "6020217" | "6080603" | "6107164" | "6117347" | "6117704" | "6153448" | "6197616" | "6207477" | "6221751" | "6245596" | "6245646").PN. OR ("6379999"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 21:11
S37	1	"6107679".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 21:11
S38	39	("5285352" | "5334857" | "5399903" | "5455456" | "5521435" | "5581122" | "5592025" | "5612576" | "5640042" | "5657550" | "5736780" | "5739588" | "5773895" | "5777381" | "5814883" | "5821608" | "5859475" | "5866942" | "5879568" | "5893508" | "5918113").PN. OR ("6107679"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 21:11
S39	78	("2636062" | "3553542" | "3573565" | "4274106" | "4777520" | "4866506" | "4942454" | "5105259" | "5208467" | "5218234").PN. OR ("5612576").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 21:28
S40	1	"20040232566"	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/04 21:33
S41	157	(semiconductor or die or dice or chip or IC) with attach$2 with direct$3 with (conduct$3 or metal$4) and (semiconductor or die or dice or chip or IC) with wiring	USPAT	OR	ON	2007/04/04 22:48

S42	12	257/e21.505	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/04 22:00
S43	4758	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/04 22:05
S44	4503	257/774	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/04 22:25
S45	694	257/772	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/04 22:25
S46	70	(semiconductor or die or dice or chip or IC) with attach$2 with without with (adhes$3 or attach$3) with (conduct$3 or metal$4) and (semiconductor or die or dice or chip or IC) with wiring	USPAT	OR	ON	2007/04/04 22:50
S47	94	(semiconductor or die or dice or chip or IC) with plac$3 with direct$3 with (conduct$3 or metal$4) and (semiconductor or die or dice or chip or IC) with wiring	USPAT	OR	ON	2007/04/04 22:51